

# Product Change Notice (PCN)

Date: **3/24/2023**

PCN Number: **PCN-0451087R-01**

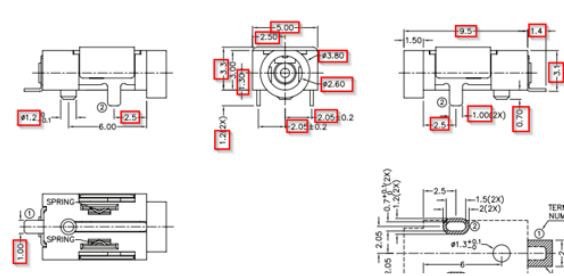

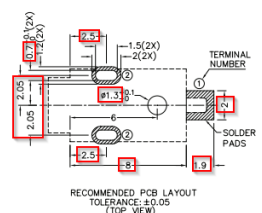

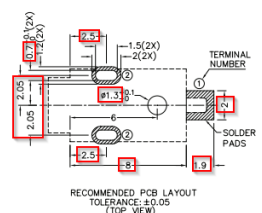


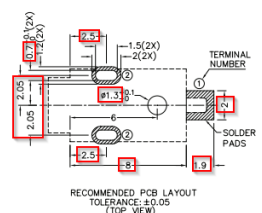
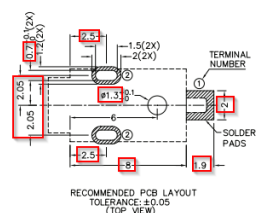
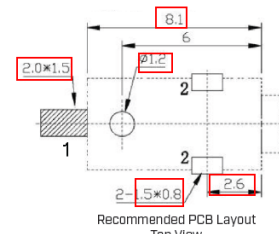
To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: PJ-039-SMT-TR

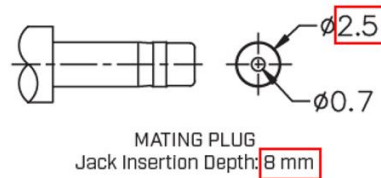
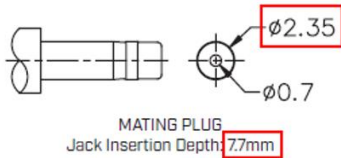
Reason(s) for Change: *Manufacturing process improvements*

Description of Change: mechanical, material, packaging, and soldering differences as shown below:

PREVIOUS CUI DEVICES DETAIL / IMAGE	NEW CUI DEVICES DETAIL / IMAGE												
 <p>35</p> <p>7</p> <table border="1"> <tr> <td>SCHMATIC</td> <td></td> <td>1</td> </tr> <tr> <td></td> <td></td> <td>2</td> </tr> <tr> <td>Model</td> <td colspan="2">PJ-039-SMT-TR</td> </tr> <tr> <td>Center Pin</td> <td colspan="2">Ø0.65 mm</td> </tr> </table>	SCHMATIC		1			2	Model	PJ-039-SMT-TR		Center Pin	Ø0.65 mm		
SCHMATIC		1											
		2											
Model	PJ-039-SMT-TR												
Center Pin	Ø0.65 mm												
 <p>RECOMMENDED PCB LAYOUT TOLERANCE: ±0.05 (TOP VIEW)</p>	 <p>Recommended PCB Layout Top View</p>												

	MATERIAL	PLATING
center pin	copper	nickel
terminal 1	brass	silver
terminal 2	copper alloy	silver
shield	stainless steel	
spring	stainless steel	
plastic	PA10T	

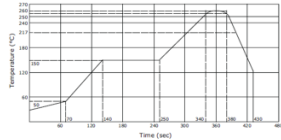
DESCRIPTION	MATERIAL	PLATING/COLOR
center pin	brass	silver
terminal 1	brass t=0.35	silver
terminal 2	phosphor bronze	silver
shield	phosphor bronze t=0.25	silver
spring	phosphor bronze t=0.25	silver
housing	PPA (UL94V-0)	black



#### SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	at relative humidity <80%		40		°C
reflow soldering <sup>1</sup>	see reflow profile	255	260	265	°C
drying conditions <sup>2</sup>	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

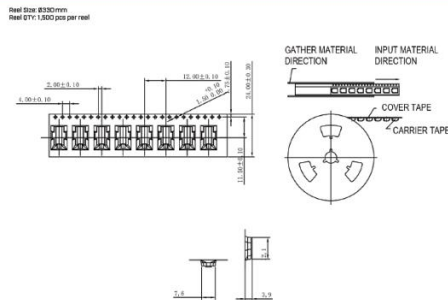
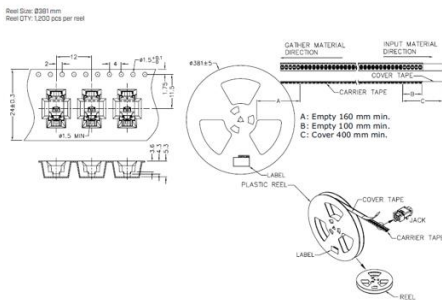
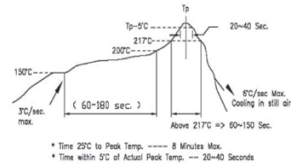
Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C @ relative humidity <60%.  
2. When exceeding floor life by >72 hours.



#### SOLDERABILITY

parameter	conditions/description	min	typ	max	units
reel storage	10-30°C, <70% humidity				°C
reflow soldering <sup>1</sup>	see reflow profile	255	260		°C
drying conditions <sup>2</sup>	parts in reel: bake at 110°C for 4 hours parts removed from reel: bake at 110°C for 4 hours				

Note: 1. CU Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature <30°C @ relative humidity <60%.  
2. When exceeding floor life by >240 hours.



Affected Date Code: 3/21/23

Product Availability: Channel Availability Q2

F-723-001

Revision: A



Additional Information:

PCN Approval:

Operations/Quality

*Rae O'Brien*

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Product Management

*RH*

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